

ENGIS[®] MICROTECH TECHNICAL DATA

CP1 POLISHING SOLUTION

A CHEMICAL POLISHING SOLUTION DESIGNED
FOR FINAL POLISHING OF
GaAs AND InP WAFERS

PRODUCT DESCRIPTION

- ◆ TYPICAL DILUTION AT 1:1 OR 1:2 RATIOS WITH DI WATER PRIOR TO USE
- ◆ EXCELLENT CHEMICAL POLISHING EFFECT ON FINAL STEP FOR GaAs AND InP WAFERS
- ◆ NON FLAMMABLE
- ◆ NO OZONE DEPLETING CHEMICALS
- ◆ CORROSIVE
- ◆ CHLORINE ODOR
- ◆ PROTECTED AGAINST BACTERIAL AND FUNGUS DETERIORATION
- ◆ EASILY REMOVED WITH WATER

TECHNICAL DATA

pH: 11.5—13.0
VISCOSITY: ~ 1 cps
SOLIDS %: NONE
DENSITY: 1.09 g/cm³

PACKAGING

1 GALLON ▪ 5 GALLON

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ADVANCED MATERIALS PRODUCTS



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MTDCP1-001-0306

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

WWW.ENGISCA.COM